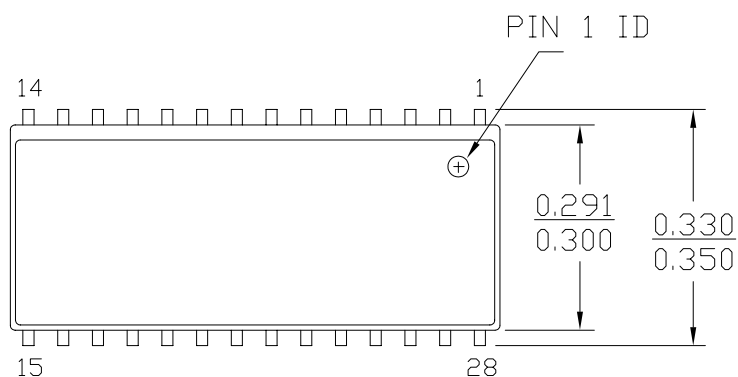


28 Lead (300 Mil) Molded SOJ V21

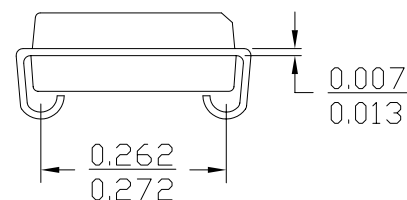
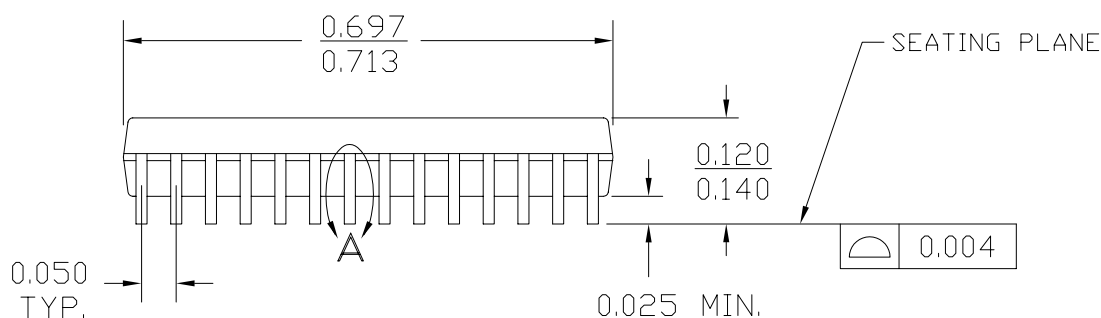
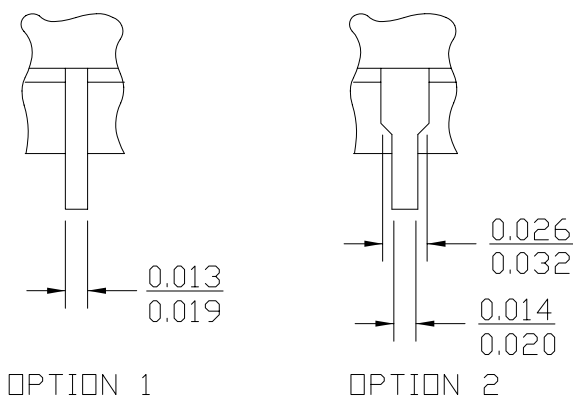
NOTE :

1. JEDEC STD REF MO088
2. BODY LENGTH DIMENSION DOES NOT INCLUDE MOLD PROTRUSION/END FLASH
MOLD PROTRUSION/END FLASH SHALL NOT EXCEED 0.006 in (0.152 mm) PER SIDE
3. DIMENSIONS IN INCHES MIN.
MAX.


REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	N/A	N/A	N/A	N/A
1	-	*A	43724	ADD DETAIL "A"	07/17/96	N/A
1	-	*B	49388	CHG. TITLE	05/29/97	N/A
1	-	*C	390613	ADD NOTES -JEDEC REFERENCE MO088 -MOLD PROTRUSION/END FLASH INFORMATION	08/05/05	N/A
1	-	*D	2871406	Changed template, & title from 28LD (300 MIL) SOJ PKG OUTLINE to PACKAGE OUTLINE, 28L SOJ 300 MILS V28.3 (MOLDED SOJ V21).	02/02/10	QAD



DETAIL A EXTERNAL LEAD DESIGN



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UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ON: DECIMALS .XX ± 0.05 .XXX ± .XXXX + ANGLES ± 1°		DESIGNED BY ONG	DATE 08/05/05	 CYPRESS Company Confidential	
		DRAWN BY ONG	DATE 08/05/05		
		CHECKED BY TSV	DATE 02/02/10		
		APPROVED BY QAD	DATE 02/02/10		
MATERIAL N/A		APPROVED BY JGUA	DATE 02/02/10	TITLE PACKAGE OUTLINE, 28L SOJ 300 MILS V28.3 (MOLDED SOJ V21)	
FINISH N/A		APPROVED BY N/A	DATE N/A	SIZE A	PART NO. V28.3
				DWG NO 51-85031	REV *D
				SCALED TO FIT N/A	SHEET 1 OF 1